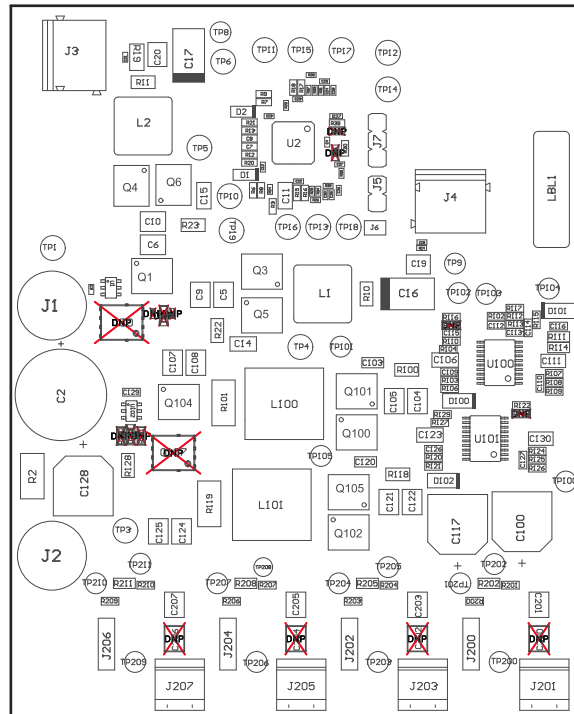
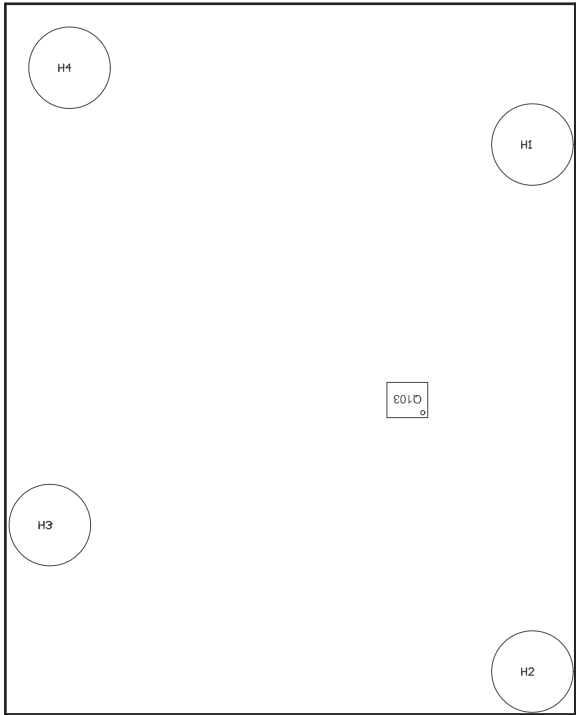


ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.  
 ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.  
 ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.  
 ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
	TID #: TIDA-01534		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/19/2017 11:31:06 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
	TID #: TIDA-01534		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/19/2017 11:31:07 AM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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